



SOT510-1

plastic thin shrink small outline package; 38 leads; body width 4.4 mm; lead pitch 0.5 mm

8 June 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP38
Package type industry code	TSSOP38
Package style descriptive code	TSSOP (thin shrink small outline package)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	2-11-2005

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		9.6	-	9.7	9.8	mm
E	package width		4.3	-	4.4	4.5	mm
A	seated height		-	-	1.1	1.1	mm
A ₂	package height		0.85	-	0.9	0.95	mm
e	nominal pitch		-	-	-	-	
n ₂	actual quantity of termination		-	-	38	-	



2. Package outline

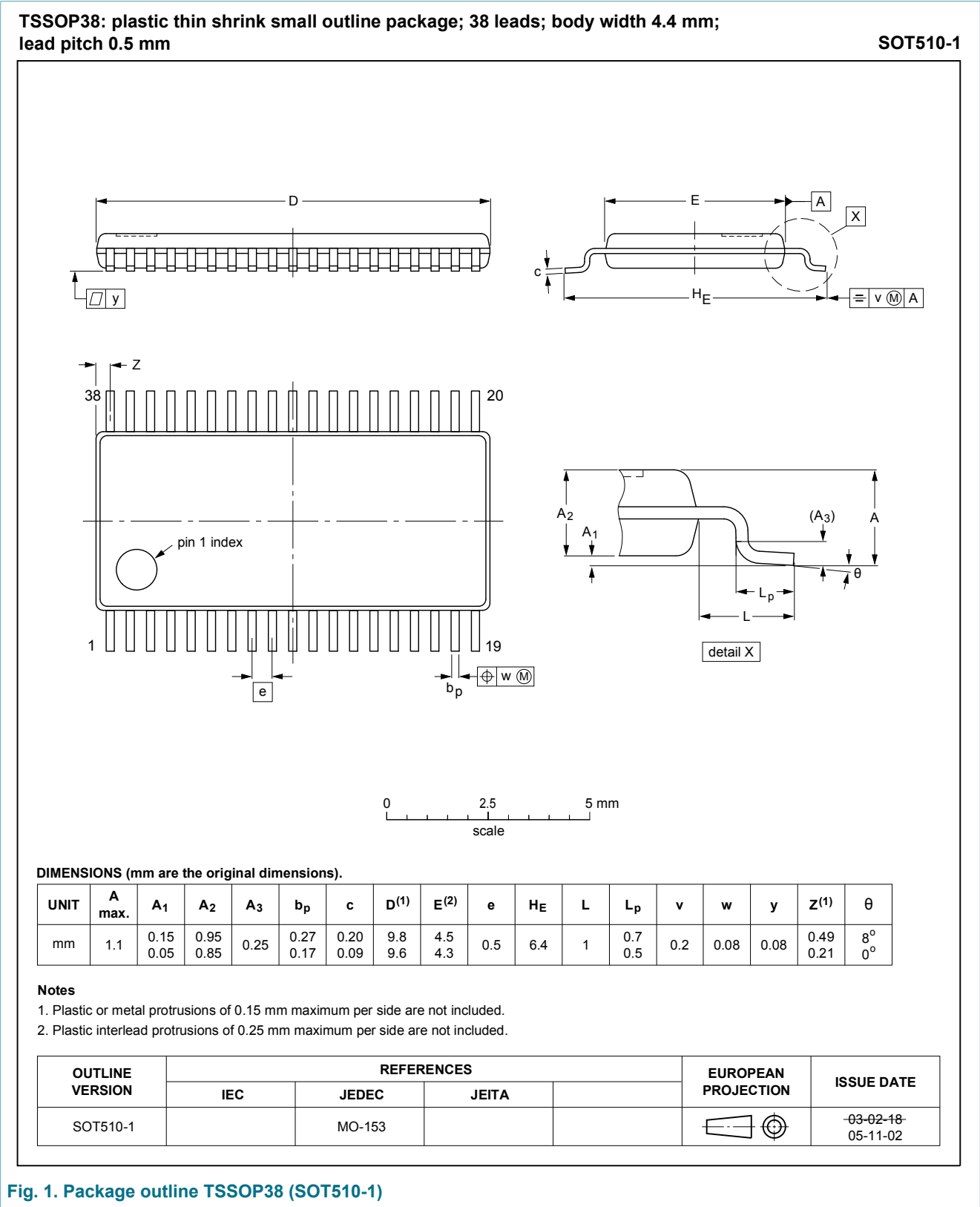


Fig. 1. Package outline TSSOP38 (SOT510-1)

4. Legal information

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